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07-16-1999

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office



To the Honorable Commissioner
original documents or copy thereof.

101092451

Please record the attached

1. Name of conveying party(ies):

- (1) Tadahiro KATO
- (2) Sadayuki OKUNI
- (3) Keiichi OKABE
- (4) Hisashi OSHIMA

Additional name(s) of conveying
party(ies) attached?

☐ yes ☒ no

2. Name and address of receiving party(ies):

Name: Shin-Etsu Handotai Co., Ltd.

Internal Address:

Street Address: Toginbiru, 4-2, Marunouchi
1-chome, Chiyoda-ku

City State Zip
Tokyo, Japan

Additional name(s) & address(es) attached?

☐ yes ☒ no

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name

Other:

Execution Date: (1) June 9, 1999
(2) June 9, 1999, 1999
(3) June 14, 1999
(4) June 9, 1999

4. Application number(s) or patent number(s): **09 348276**
If this document is being filed together with a new application, the execution date of
the application is: **July 7, 1999**

A. Patent Application No.(s)

B. Patent No(s).

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom
correspondence concerning document
should be mailed:

**Evenson, McKeown, Edwards
& Lenahan, P.L.L.C.
1200 G Street, N.W., Suite 700
Washington, D.C. 20005**

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41): \$ 40.00
☒ Enclosed. Please charge any underpayment in
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05-1323

☐ Authorized to be charged to Deposit Account

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy
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Name J. D. Evans Reg. No. 26,269

July 7, 1999
Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS, AND DOCUMENT: 4

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PATENT
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ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto:

Shin-Etsu Handotai Co., Ltd.
Toginbiru, 4-2, Marunouchi 1-chome, Chiyoda-ku,
Tokyo, Japan

(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to:

MANUFACTURING PROCESS FOR SEMICONDUCTOR WAFER

as set forth in his United States Patent Application (check one):

 X executed concurrently herewith,
 executed on _____
 Serial No. _____, filed _____,

in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefor or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of **EVENSON, McKEOWN, EDWARDS & LENAHAN, P.L.L.C.**, or any member thereof, the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and trademark Office for recordation of this Assignment.

June 9, 1999
(date)

Tadahiro Kato
(signature of 1st inventor)
Tadahiro KATO
c/o Shin-Etsu Handotai Co., Ltd., Shirakawa R&D Center
150, Oaza, Odakura, Aza, Ohira, Nishigo-mura,
Nishishirakawa-gun, Fukushima-ken, Japan

Takao Takenaka
(signature of witness)

June 9, 1999
(date)

Sadayuki Okuni
(signature of 2nd inventor)
Sadayuki OKUNI
c/o Shin-Etsu Handotai Co., Ltd., Shirakawa R&D Center
150, Oaza, Odakura, Aza, Ohira, Nishigo-mura,
Nishishirakawa-gun, Fukushima-ken, Japan

Takao Takenaka
(signature of witness)

(date)

(signature of 3rd inventor)
Keiichi OKABE
c/o Nagano Denshi Co., Ltd.
1393, Oaza, Yashiro, Kosyoku-shi, Nagano-ken, Japan

(signature of witness)

ASSIGNMENT

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as set forth in his United States Patent Application (check one):

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 executed on _____
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(date)

(signature of 1st inventor)

(signature of witness)

Tadahiro KATO
c/o Shin-Etsu Handotai Co., Ltd., Shirakawa R&D Center
150, Oaza, Odakura, Aza, Ohira, Nishigo-mura,
Nishishirakawa-gun, Fukushima-ken, Japan

(date)

(signature of 2nd inventor)

(signature of witness)

Sadayuki OKUNI
c/o Shin-Etsu Handotai Co., Ltd., Shirakawa R&D Center
150, Oaza, Odakura, Aza, Ohira, Nishigo-mura,
Nishishirakawa-gun, Fukushima-ken, Japan

(date)

(signature of 3rd inventor)

(signature of witness)

Keiichi OKABE
c/o Nagano Denshi Co., Ltd.
1393, Oaza, Yashiro, Kosyoku-shi, Nagano-ken, Japan

June
6. 9. 1999
(date)

Hisashi Oshima
(signature of 4th inventor)

Hisashi OSHIMA

c/o Naoetu Denshi Co., Ltd.

596-2, Oaza, Jyonokoshi-Shinden, Kubiki-mura, Nakakubiki-gun,
Niigata-ken, Japan

Y. Yoshimura
(signature of witness)

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